

國立交通大學

材料科學與工程學系

碩士論文

利用晶圓接合技術降低金屬誘發側向結晶

之複晶矽薄膜中殘餘金屬

~鎳過濾與鎳捕捉~



Reduction of Metal Residual in MILC Poly-Silicon

Thin Film by Wafer Bonding Method

~ Ni Filter & Ni Gettering ~

研究生：林其慶

指導教授：吳耀銓 博士

中華民國九十五年六月

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